

Please amend the following claims 1, 11 and 12.

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1. (Twice Amended) An integrated circuit inductor comprising:

a substrate;

CI a spiral inductor metalization pattern disposed on the substrate including a plurality of parallel tracks in a spiral pattern each track having a first end and a second end and having the first ends coupled together and the second ends coupled together; and

a  $n^+$  diffusion layer disposed in the substrate directly underneath the spiral inductor metalization pattern; the  $n^+$  diffusion layer has a fingered pattern shape with  $n^+$  fingers electrically isolated by regions of polysilicon.

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11.(Twice Amended) The integrated circuit inductor of claim 1, in which the fingered pattern is coupled to a common ground reference.

C2 12.(Twice Amended) The integrated circuit inductor of claim 11, in which the  $n^+$  diffusion layer further comprises a second fingered pattern coupled to the common ground reference by a conductive strip that does not provide a ground loop path.

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